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To the Honorable Director of the United States Patent and Trademark Office: Please record the attached original documents or copy thereof.

1. Name of conveying party(ies):

Hideaki Miyamoto
Wataru Nishida
Tetsuo Shimizu

Additional names(s) of conveying party(ies)

☐ Yes ☐ No

2. Name and address of receiving party(ies):

Name: STEC INC.

Address: 2, Miyanohigashi-cho, Kisshoin, Minami-ku

City: Kyoto

State/Prov.: _____

Country: Japan

ZIP: _____

Additional name(s) & address(es)

☐ Yes ☒ No

3. Nature of conveyance:

☒ Assignment

☐ Merger

☐ Security Agreement

☐ Change of Name

☐ Other _____

Execution Date: May 30, 2003

4. Application number(s) or patent numbers(s):

If this document is being filed together with a new application, the execution date of the application is:

Patent Application No.

Filing date

B. Patent No.(s)

10/386,318

03/11/2003

Additional numbers

☐ Yes ☒ No

FINANCE SECTION

JUN 17 AM 6:46

5. Name and address of party to whom correspondence concerning document should be mailed:

Name: Joseph W. Price

Registration No. 25,124

Address: SNELL & WILMER LLP

1920 Main Street, Suite 1200

06/23/2003 ECDOPER 00000109 192814 10386318

01 FC:8021 40.00 DA

City: Irvine

State/Prov.: CA

Country: USA

ZIP: 92614

6. Total number of applications and patents involved:

1

7. Total fee (37 CFR 3.41):.....\$ 40.00

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9. Statement and signature.

To the best of my knowledge and belief, the foregoing information is true and correct and any attached copy is a true copy of the original document.

Joseph W. Price

Name of Person Signing

Signature

June 17, 2003

Date

3

Total number of pages including cover sheet, attachments, and

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PATENT

REEL: 014188 FRAME: 0914

ASSIGNMENT

WHEREAS, I/we, Hideaki MIYAMOTO, Wataru NISHIDA and Tetsuo SHIMIZU

(hereinafter "Assignor(s)"), citizen(s) of Japan, have invented certain new and useful improvements in a LIQUID MATERIAL EVAPORATION APPARATUS FOR SEMICONDUCTOR MANUFACTURING

for which I/we have executed application for Letters Patent of the United States, filed March 11, 2003 assigned Serial Number 10/386,318

WHEREAS, STEC INC.

hereinafter "Assignee"), a corporation of Japan, having a principal place of business at 2, Miyanohigashi-cho, Kisshoin, Minami-ku, Kyoto, Japan

is desirous of obtaining the entire right, title and interest in, to and under the said improvements and the said application,

NOW, THEREFORE, in consideration of the sum of One Hundred Yen (¥100) to me/us in hand paid, and other good and valuable consideration, the receipt of which is hereby acknowledged, I/we, the Assignor(s) have sold, assigned, transferred and set over, unto said Assignee, its successors, legal representatives and assigns, the entire right, title and interest in, to and under said improvements, and said application and all divisions, renewals and continuations thereof, and all Letters Patents of the United States, which may be granted thereon and all reissues and extensions thereof, and all priority rights under the International Convention for the Protection of Industrial Property for every country of the Union, and all applications for Letters Patents which may hereafter be filed for said improvements in any country or countries foreign to the United States, and all Letters Patents which may be granted for said improvements in any country or countries foreign to the United States, and any official of any country or countries foreign to the United States, whose duty it is to issue patents, on applications as aforesaid, to issue all Letters Patents for said improvements to said Assignee, its successors, legal representatives and assigns, in accordance with the terms of this instrument.

AND I/WE, HEREBY covenant that I/we have full right to convey the entire interest herein assigned, and that I/we have not executed, and will not execute, any agreement in conflict herewith.

AND I/WE HEREBY further covenant and agree that I/we will communicate to said Assignee, its successors, legal representatives and assigns, any facts known to me/us respecting said improvements, and testify in any legal proceeding, sign all lawful papers, execute all divisional, continuing and reissue applications, make all rightful oaths and generally do everything

possible to aid said Assignee, its successors, legal representatives and assigns, to obtain and enforce proper patent protection for said improvements in all countries.

IN TESTIMONY WHEREOF, I hereunto set my hand this 30th
day of May, 2003.

Hideaki Miyamoto
(Inventor) Hideaki MIYAMOTO

IN TESTIMONY WHEREOF, I hereunto set my hand this 30th
day of May, 2003.

Wataru Nishida
(Inventor) Wataru NISHIDA

IN TESTIMONY WHEREOF, I hereunto set my hand this 30th
day of May, 2003.

Tetsuo Shimizu
(Inventor) Tetsuo SHIMIZU